D OR PW PACKAGE (TOP VIEW)

14 VCC

13 4B

12 4A

11 **1** 4Y

10 **1** 3B

9 🛛 3A

8 🛛 3Y

1A [

1B 🛛 2

1Y 🛛 3

4

5

2A 🛛

2B 🛛

2Y 🛛 6

GND 7

SCLS490 - JUNE 2003

- Controlled Baseline
 One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- EPIC[™] (Enhanced-Performance Implanted CMOS) Process
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

description/ordering information

The SN74AHCT08 is a quadruple 2-input positive-AND gate. This device performs the Boolean function $Y = A \bullet B$ or $Y = \overline{\overline{A} + \overline{B}}$ in positive logic.

ORDERING INFORMATION

TA	PACK/	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
55°C to 125°C	SOIC – D	Tape and reel	SN74AHCT08MDREP	AHCT08MEP
-55 C 10 125 C	TSSOP – PW	Tape and reel	SN74AHCT08MPWREP	AHT08EP

Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

(each gate)									
INP	UTS	OUTPUT							
Α	В	Y							
Н	Н	Н							
L	Х	L							
Х	L	L							



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SCLS490 - JUNE 2003

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC}	\ldots –0.5 V to 7 V
Input voltage range, V _I (see Note 1)	\ldots –0.5 V to 7 V
Output voltage range, VO (see Note 1)	\ldots –0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T _{stg}	$\dots \dots -65^{\circ}C$ to $150^{\circ}C$

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage	0	5.5	V
Vo	Output voltage	0	VCC	V
IОН	High-level output current		-8	mA
IOL	Low-level output current		8	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-55	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCLS490 - JUNE 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	Vee	Т	₄ = 25°C	;	MINI	MAY	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX		WAA	UNIT
Vau	I _{OH} = -50 μA	45.1	4.4	4.5		4.4		V
⊻ОН	I _{OH} = -8 mA	4.5 V	3.94			3.8		v
Ve	I _{OL} = 50 μA	451/			0.1		0.1	V
VOL	I _{OL} = 8 mA	4.5 V			0.36		0.44	v
li li	$V_{I} = 5.5 \text{ V or GND}$	0 V to 5.5 V			±0.1		±1	μA
ICC	$V_{I} = V_{CC} \text{ or } GND, I_{O} = 0$	5.5 V			2		20	μΑ
∆lcc [†]	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			1.35		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		4	10			pF

[†] This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	T _A = 25°C		T _A = 25°C		MIN	MAY	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIN				
^t PLH	A or P	V	C _L = 15 pF		5	6.9	1	8	20		
^t PHL	AUB	T			5	6.9	1	8	115		
^t PLH	A or P	V	$C_{\rm L} = 50 \rm pF$		5.5	7.9	1	9	20		
^t PHL	AUB	T	CL = 50 pF		5.5	7.9	1	9	ns		

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.4	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.4	-0.8	V
VOH(V)	Quiet output, minimum dynamic V _{OH}	4.4			V
VIH(D)	High-level dynamic input voltage	2			V
V _{IL(D)}	Low-level dynamic input voltage			0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	18	pF



SCLS490 - JUNE 2003



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74AHCT08MDREP	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT08MEP	Samples
SN74AHCT08MPWREP	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT08EP	Samples
V62/03654-01XE	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT08EP	Samples
V62/03654-01YE	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT08MEP	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74AHCT08-EP :

• Catalog: SN74AHCT08

• Military: SN54AHCT08

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	All dimensions are nominal											
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT08MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT08MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

16-Oct-2020



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT08MDREP	SOIC	D	14	2500	333.2	345.9	28.6
SN74AHCT08MPWREP	TSSOP	PW	14	2000	853.0	449.0	35.0

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